2026 IEEE MTT-S

International Microwave Workshop Series
on Advanced Materials and Processes
for RF and THz Applications (IMWS-AMP 2026)

Call for Papers

July 22 - 24, 2026

Pullman Reef Hotel, Cairns, Australia

https://imws-amp.org

Organizing Committee

General Chair
Yang Yang, University of Technology Sydney, Australia

General Co-Chair
Tao Huang, James Cook University, Australia

Technical Program Committee Chair
Withawat Withayachumnankul, The University of Adelaide, Australia

Technical Program Committee Co-Chairs
Konstanty Bialkowski, University of Queensland, Australia
Amir Ebrahimi, RMIT, Australia
Si-Ping Gao, Nanjing University of Aeronautics and Astronautics, China
Zhihao Jiang, Southeast University
Naixing Feng, Anhui University, China
Wenjie Feng, South China University of Technology, China
He Zhu, Commonwealth Scientific and Industrial Research Organisation (CSIRO), Australia

International Advisory Committee Chairs
Yongxin Guo, City University of Hong Kong, China
Ke Wu, University of Montreal, Canada
Maurizio Bozzi, University of Pavia, Italy
Kamran Ghorbani, RMIT, Australia
Wenquan Che, South China University of Technology, China

Finance Chair
Zhichao (Bryan) Sun, University of Technology Sydney, Australia

Exhibition and Sponsorship Chair
Maral Ansari, Commonwealth Scientific and Industrial Research Organisation (CSIRO), Australia

Young Professional and Student Events Chairs
Syed Abbas, Macquarie University, Australia
Yafei Wu, University of Electronic Science and Technology of China

Publicity Chairs
Xiaojing Lv, University of Technology Sydney, Australia

Local Arrangements Chair & Conference Secretariat
Peter Beadle, Academic Event Services

Email: info2026@imws-amp.org

IEEE MTT-S International Microwave Workshop Series on Advanced Materials and Processes for RF and THz Applications (IMWS-AMP 2026) is organized by the University of Technology Sydney (UTS). IMWS-AMP 2026 is a continuation of a series of annual international events held in Suzhou, China (2015), Chengdu, China (2016), Pavia, Italy (2017), Michigan, USA (2018), Bochum, Germany (2019), Suzhou, China (2020), Chongqing, China (2021), Guangzhou, China (2022), Chengdu, China (2023), Nanjing, China (2024) and Wuxi, China (2025). The purpose of this platform is to boost technical and educational activities as well as exchange and collaborations within the international microwave community.

IMWS-AMP 2026 will be held in Cairns, Australia, on July 22 - 24, 2026. IMWS-AMP 2026 will feature both invited and contributed papers. Distinguished researchers will be invited to deliver keynote speeches on technological trends and significant advances in relevant topics. Contributed papers are solicited for the same topics as listed below.

The topics include, but are not limited to:

Track 1: Advanced Materials for RF and Microwave

- 2D materials and carbon nanotubes for electronic and optoelectronic devices
- Wide bandgap and emerging semiconductors for high-frequency applications
- Magnetic, superconducting, and spin-wave materials for RF and THz

Track 2: Innovative Manufacturing and Integration

- Additive and large-area manufacturing (3D printing, inkjet) for RF and THz components
- Advanced packaging and integration for 5G, mmWave, and IoT
- Ceramic and polymer-based substrates for microwave devices

Track 3: Flexible and Wearable Antennas and Systems

- Flexible materials and processes for RF electronics and antennas
- Integrated antennas and RF components for wearable IoT devices

Track 4: Metamaterials and Intelligent Wave Engineering

- Metamaterials and plasmonics for absorption, cloaking, and wave manipulation
- Antennas leveraging artificial and engineered materials
- Reconfigurable Intelligent Surfaces (RIS) for smart wireless environments

Track 5: Integrated Microwave and THz Devices

- Passive and active microwave/THz devices including filters, amplifiers, modulators, etc.

Track 6: Advanced Applications and Characterization

- Wireless communications, radar, imaging, and sensing
- Material characterization for RF, microwave, and THz technologies

Electronic Paper Submission:

Prospective authors are invited to submit manuscripts in electronic (PDF) format only through EDAS at https://edas.info/newPaper.php?c=34661. All papers must be written in English and limited to three pages. Papers submitted will be peer-reviewed, and all papers presented at the conference will be included in the IEEE Xplore pending quality review. Note that one-page abstracts can also be acceptable, but they will not be included in the IEEE Xplore.

Special Issue in IEEE Transactions on Microwave Theory and Techniques (IEEE T-MTT):

Authors of all papers presented at IEEE IMWS-AMP 2026 are invited to submit an expanded version of their papers to a Mini-Special Issue of the IEEE T-MTT. A significant extension of the conference paper is required, so that the novelty and quality of the manuscript are the same as that of regular manuscripts of IEEE T-MTT. Every paper will be reviewed in the same manner as all other regular submissions.

Best Student Paper Awards:

Awards for Best Student Papers will be presented to the winners at the conference. The Awards Committee will judge the papers primarily on originality, significance, technical soundness, presentation, and reviewers' reports. To qualify for the Best Student Paper, the author must be a full-time student who presents, as the first author, the paper at the conference.

Exhibitions:

Exhibition of company products is solicited for the areas related to the topics. Interested parties should contact the Conference Secretariat.

Important Dates

Paper Submission Deadline: February 25, 2026
Notification of Acceptance: April 2, 2026
Final Paper Submission: April 16, 2026